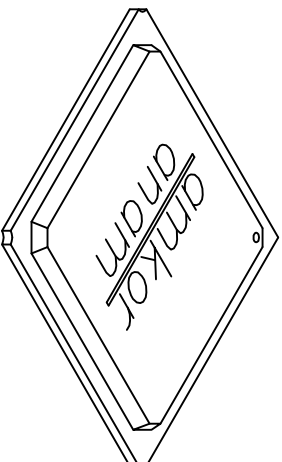


REVISION HISTORY				
REV	DESCRIPTION	ISSUED FILE NAME	ORDERED FILE NAME	DATE
00	INITIAL RELEASE	Y.M.A.C.	N/A	D.R.A.
01	UPDATE	Y.M.A.C.	N/A	03/27/96
02	REDRAWN & REVISED	D.R.A.	N/A	08/21/96
03	CHANGED CAP TOLERANCE.	M.W.	N/A	03/16/95
04	UPDATED 388 BALL MATRIX TO 388-1	PGONZ	N/A	12/28/00



- NOTES: UNLESS OTHERWISE SPECIFIED
1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994.
2. THE BASIC SOLDER BALL GRID PITCH IS 1.27mm.
3. THE MAXIMUM SOLDER BALL MATRIX SIZE IS 28 X 26.
4. THE MAXIMUM ALLOWABLE NUMBER OF SOLDER BALLS IS 676.
5. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C.
6. PRIMARY DATUM Z AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
7. A1 BALL PAD CORNER I.D. FOR PLATE MOLD: TO BE MARKED BY INK.
AUTO MOLD: DIMPLE TO BE FORMED BY MOLD CAP
- REFERENCE SPECIFICATIONS:
- A. AAWW SPEC #001-0531-2234: PACKING OPERATION PROCEDURE.
- B. AAWW SPEC #001-0519-2082: MARKING.
- C. THIS DRAWING CONFORMS TO THE JEDEC REGISTERED OUTLINE MS-034/A VARIATION BAR-2 EXCEPT FOR ϕ DIMENSION.
- JEDEC(AWKOR) DIM ϕ MIN NOM $0.20(0.15)$ MAX

[illegible]